APL3015SYCK SUPER BRIGHT YELLOW

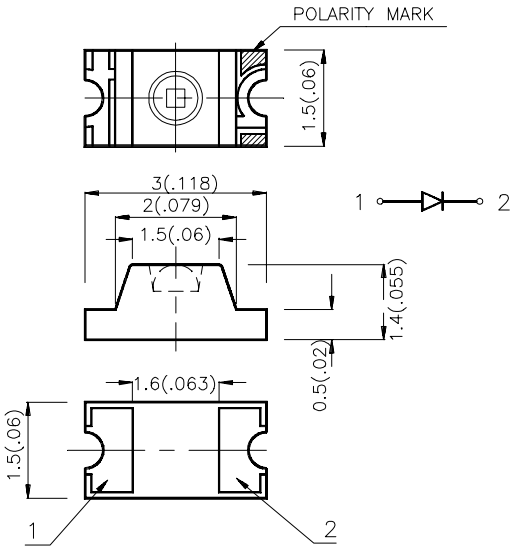
Features

- 3.0mmx1.5mm SMT LED, 1.4mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- INNER LENS TYPE.
- PACKAGE : 2000PCS / REEL.

Description

The Super Bright Yellow source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.0079") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APL3015SYCK	SUPER BRIGHT YELLOW (InGaAlP)	WATER CLEAR	40	100	70°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

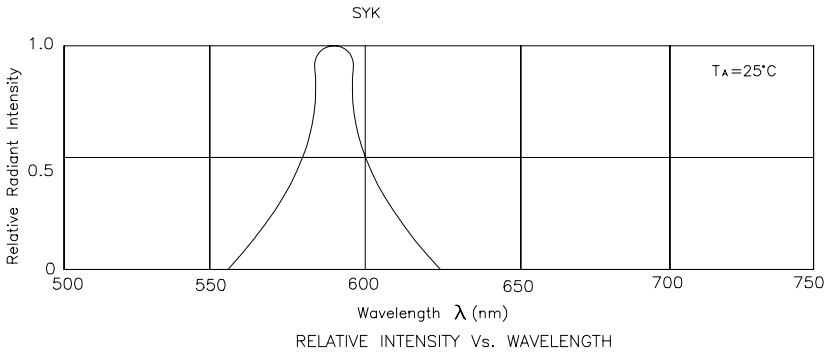
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λ D	Dominate Wavelength	Super Bright Yellow	590		nm	IF=20mA
Δλ1/2	Spectral Line Halfwidth	Super Bright Yellow	20		nm	IF=20mA
C	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
V_F	Forward Voltage	Super Bright Yellow	2.0	2.5	V	IF=20mA
I_R	Reverse Current	Super Bright Yellow		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

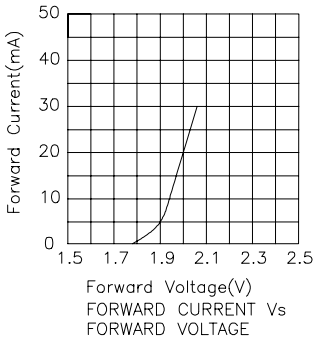
Parameter	Super Bright Yellow	Units
Power dissipation	125	mW
DC Forward Current	30	mA
Peak Forward Current [1]	175	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

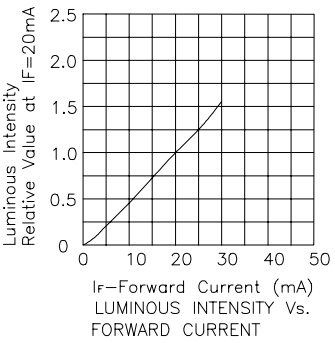


RELATIVE INTENSITY Vs. WAVELENGTH

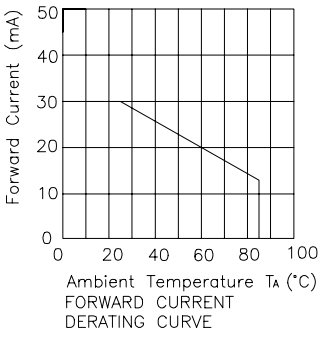
Super Bright Yellow APL3015SYCK



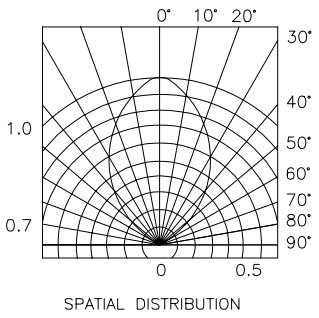
FORWARD CURRENT Vs
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



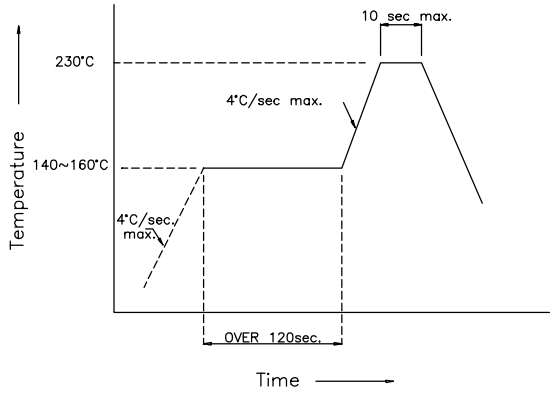
FORWARD CURRENT
DERATING CURVE



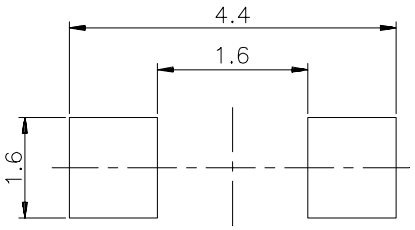
SPATIAL DISTRIBUTION

APL3015SYCK
SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern
(Units : mm)



Tape Specifications
(Units : mm)

